

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	42	"257"/\$.ccls. and UBM and adhesive and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 09:45
S2	42	"257"/\$.ccls. and (UBM or (under adj ball adj metallurgy)) and adhesive and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/03/22 18:00
S3	64	"257"/\$.ccls. and (UBM or (under adj ball adj (metallurgy or metallization))) and (adhesive or epoxy) and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/03/22 18:20
S4	74	"438"/\$.ccls. and (UBM or (under adj ball adj (metallurgy or metallization))) and (adhesive or epoxy) and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/03/22 18:47
S5	338	438/106.ccls. and @pd>"20020520"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/03/22 19:03
S6	266	438/108.ccls. and @pd>"20020520"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/03/22 19:10
S7	80	438/614.ccls. and @pd>"20020520"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/03/22 19:14
S8	133	257/783.ccls. and @pd>"20020520"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/03/22 19:15
S9	2	"20010021541".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/03/23 15:02
S10	2	"6355507".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/03/23 15:02

S11	109	(polymer or polymeric) with (bismaleimide adj triazine)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/01/08 10:01
S12	81	((polymer or polymeric) with (bismaleimide adj triazine)) and adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/15 20:31
S13	2	((polymer or polymeric) with (bismaleimide adj triazine)) and (adhesive with (microns micrometers))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/15 20:34
S14	19	((polymer or polymeric) with (bismaleimide adj triazine)) and (adhesive with thick\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/15 20:40
S15	4695	((polymer or polymeric) with (substrate)) and (adhesive with thick\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/15 20:40
S16	168	((polymer or polymeric) with (substrate)) with (adhesive near5 thick\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/15 20:41
S17	114	"257"/\$.ccls. and singulation with saw\$3 and @ad<"20010330"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/17 13:07
S18	149	"257"/\$.ccls. and (substrate with (bismaleimide adj triazine)) and @ad<"20010330"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/17 13:20
S19	13	"257"/\$.ccls. and (substrate with (polymer polymeric) with (bismaleimide adj triazine)) and @ad<"20010330"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/17 13:16
S20	17	"257"/\$.ccls. and (adhesive with polyimide with thermocompress\$3) and @ad<"20010330"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/17 13:17

S21	0	"257"/\$.ccls. and (substrate with (bismaleimide adj triazine)) and (adhesive with polyimide with thermocompress\$3) and @ad<"20010330"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/17 13:21
S22	0	"257"/\$.ccls. and (substrate with (polymer polymeric)) and (adhesive with polyimide with thermocompress\$3) and @ad<"20010330"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/17 13:21
S23	16888	(die chip) same substrate same (adhesive adhesion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/05 16:13
S24	1695	(die chip) same substrate same (adhesive adhesion) and (singulation saw sawing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/06 16:16
S25	412	(die chip) same substrate same (opening openings via) same (adhesive adhesion) and (singulation saw sawing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/06 16:18
S26	33	((("20020163055") or ("20020170746") or ("5882956") or ("20010021541") or ("6355507") or ("6265782") or ("6232147") or ("5480835") or ("5846875") or ("20010021541") or ("6355507") or ("6265782") or ("6232147") or ("5480835") or ("5846875") or ("6064114") or ("6075710") or ("5994766") or ("6118183") or ("6137164") or ("5734201") or ("5914533"))).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/25 13:40
S27	239	"257"/\$.ccls. and UBM and adhesive and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 09:46
S28	51672	"257"/\$.ccls. and UBM (die chip) and (substrate with (opening via))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/03 09:47
S29	286	"257"/\$.ccls. and UBM and (die chip) and (substrate with (opening via))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/03 09:54

S30	286	"257"/\$.ccls. and UBM and (die chip) and (substrate with (opening via throughhole through-hole))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/03 10:58
S31	187	"438"/\$.ccls. and UBM and (die chip) and (substrate with (opening via throughhole through-hole))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/03 10:46
S32	38	"438"/\$.ccls. and UBM and (die chip) and (substrate with hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/03 10:49
S33	59	"257"/\$.ccls. and UBM and (die chip) and (substrate with hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/03 10:49
S34	12525	"257"/\$.ccls. and (copper cu nickel ni) and (die chip) and (substrate with (opening via throughhole through-hole))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/03 10:59
S35	2875	"257"/\$.ccls. and ((die chip) with (copper cu nickel ni)) and (substrate with (opening via throughhole through-hole))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/03 10:59